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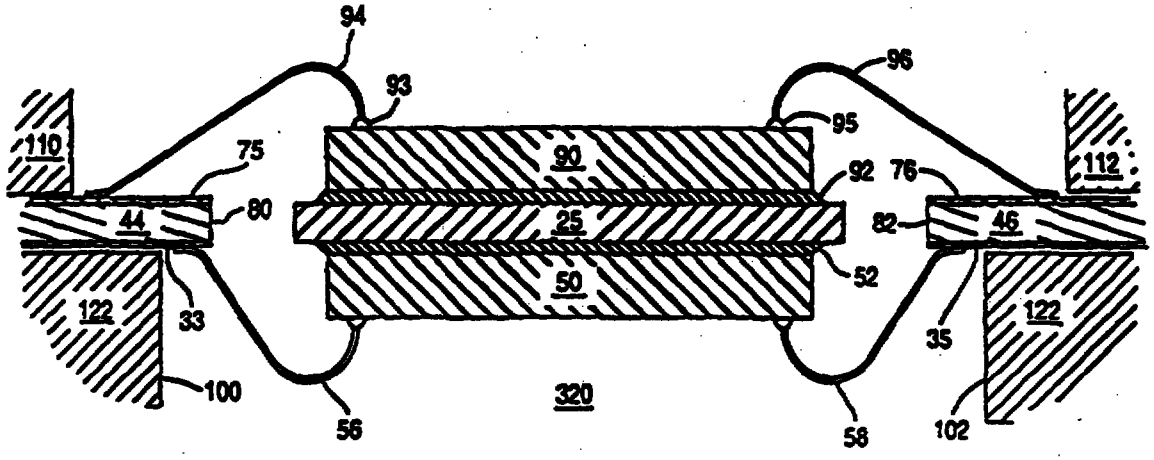
(54) Title: MANUFACTURING DUAL SIDED WIRE BONDED INTEGRATED CIRCUIT CHIP PACKAGES USING OFFSET WIRE BONDS AND SUPPORT BLOCK CAVITIES



(57) Abstract

A method is disclosed for constructing a dual sided chip package onto a leadframe (20) having a die pad (25) and a set of lead fingers (40, 42) corresponding to the die pad. Integrated circuit dies (50, 90) are disposed onto each side of the die pad while the leadframe is supported with support blocks (118, 122) having cavities (120, 320) that accept the integrated circuit dies and that support each lead finger and that provide clearance for stitch bonds (56, 58, 94, 96) of the previously formed wire bonds. Thereafter, a one step plastic mold (66) is formed around each assembly comprising the dual integrated circuit dies, the die pads, and the wire bonds.

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